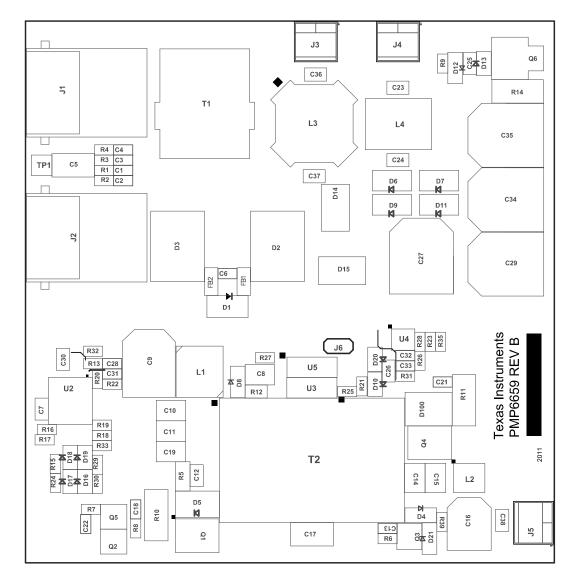
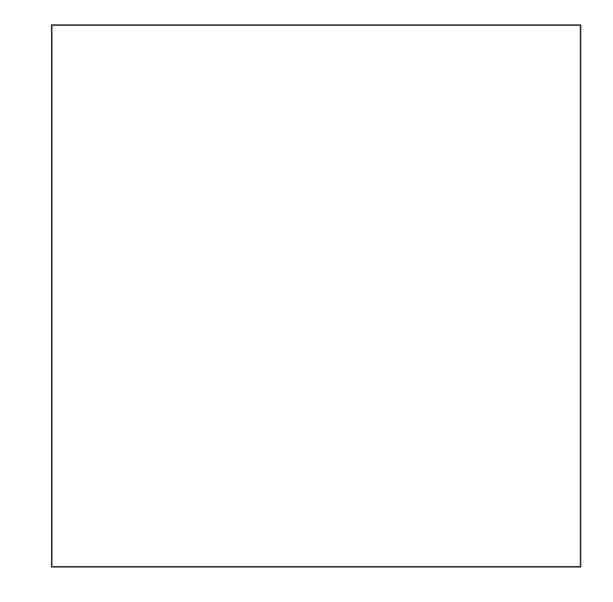
- ZZ2 These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZ3 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ4 These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS ASSEMBLY VARIANT: [No Variations]

| PCB VIEWED FROM TOP SIDE | BOARD #: PMP6659 | REV: B | SVN REV | : Not In VersionControl |
|----------------------------------|--------------------|------------|---------|-------------------------|
| IGNORE -> Top Overlay | | | | |
| PLOT NAME = Top Assembly Drawing | GENERATED : 1/9/20 | 14 4:18:52 | PM | TEXAS INSTRUMENTS |



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS ASSEMBLY VARIANT: [No Variations]

| PCB VIEWED FROM BOTTOM SIDE | BOARD #: PMP6659 | REV: B | SVN REV: | : Not In VersionControl |
|-------------------------------------|--------------------------|-----------------|----------|-------------------------|
| | Bottom Overlay <- SNONDI | | | |
| PLOT NAME = Bottom Assembly Drawing | GENERATED : 1/9/20 | 4: 18:52 | PM | TEXAS INSTRUMENTS |

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